

# SSTU32866

1.8 V 25-bit 1:1 or 14-bit 1:2 configurable registered buffer with parity for DDR2 RDIMM applications

Rev. 02 — 11 November 2004

Product data sheet

## 1. General description

The SSTU32866 is a 1.8 V configurable register specifically designed for use on DDR2 memory modules requiring a parity checking function. It is defined in accordance with the JEDEC JESD82-7 standard for the SSTU32864 registered buffer, while adding the parity checking function in a compatible pinout. The JEDEC standard for SSTU32866 is pending publication. The register is configurable (using configuration pins C0 and C1) to two topologies: 25-bit 1:1 or 14-bit 1:2, and in the latter configuration can be designated as Register A or Register B on the DIMM.

The SSTU32866 accepts a parity bit from the memory controller on its parity bit (PAR\_IN) input, compares it with the data received on the DIMM-independent D-inputs and indicates whether a parity error has occurred on its open-drain  $\overline{\text{QERR}}$  pin (active-LOW). The convention is even parity, that is, valid parity is defined as an even number of ones across the DIMM-independent data inputs combined with the parity input bit.

The SSTU32866 is packaged in a 96-ball,  $6 \times 16$  grid, 0.8 mm ball pitch LFBGA package (13.5 mm by 5.5 mm).

## 2. Features

- Configurable register supporting DDR2 Registered DIMM applications
- Configurable to 25-bit 1:1 mode or 14-bit 1:2 mode
- Controlled output impedance drivers enable optimal signal integrity and speed
- Exceeds JESD82-7 speed performance (1.8 ns max. single-bit switching propagation delay; 2.0 ns max. mass-switching)
- Supports up to 450 MHz clock frequency of operation
- Optimized pinout for high-density DDR2 module design
- Chip-selects minimize power consumption by gating data outputs from changing state
- Supports SSTL\_18 data inputs
- Checks parity on the DIMM-independent data inputs
- Partial parity output and input allows cascading of two SSTU32866s for correct parity error processing
- Differential clock (CK and  $\overline{\text{CK}}$ ) inputs
- Supports LVCMOS switching levels on the control and  $\overline{\text{RESET}}$  inputs
- Single 1.8 V supply operation
- Available in 96-ball,  $13.5 \times 5.5$  mm, 0.8 mm ball pitch LFBGA package

**PHILIPS**



3. Applications

- DDR2 registered DIMMs desiring parity checking functionality

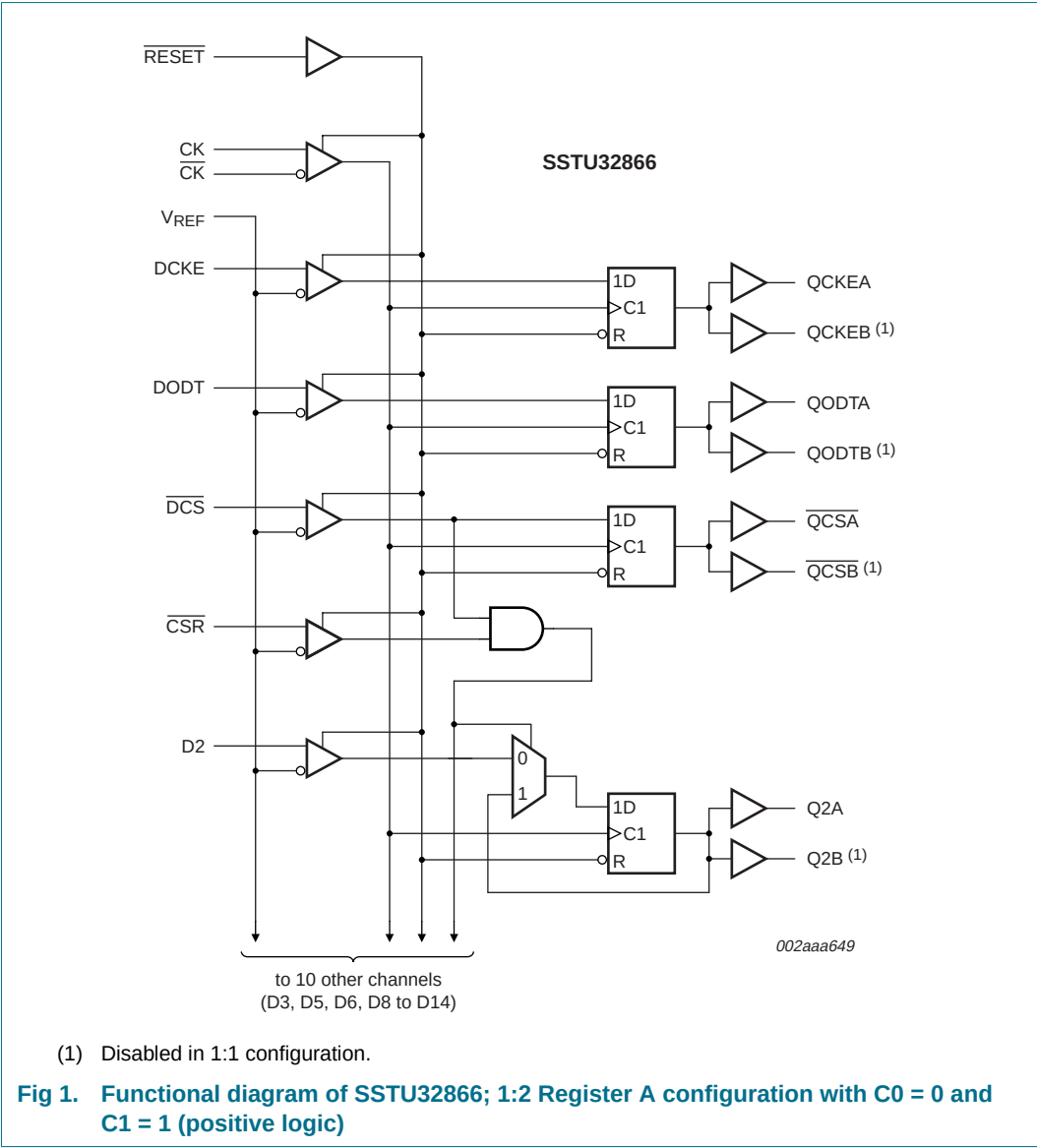
4. Ordering information

Table 1: Ordering information

$T_{amb} = 0\text{ }^{\circ}\text{C}$  to  $+70\text{ }^{\circ}\text{C}$ .

| Type number   | Solder process                        | Package |                                                                                                                |          |
|---------------|---------------------------------------|---------|----------------------------------------------------------------------------------------------------------------|----------|
|               |                                       | Name    | Description                                                                                                    | Version  |
| SSTU32866EC/G | Pb-free (SnAgCu solder ball compound) | LFBGA96 | plastic low profile fine-pitch ball grid array package; 96 balls; body $13.5 \times 5.5 \times 1.05\text{ mm}$ | SOT536-1 |
| SSTU32866EC   | SnPb solder ball compound             | LFBGA96 | plastic low profile fine-pitch ball grid array package; 96 balls; body $13.5 \times 5.5 \times 1.05\text{ mm}$ | SOT536-1 |

5. Functional diagram



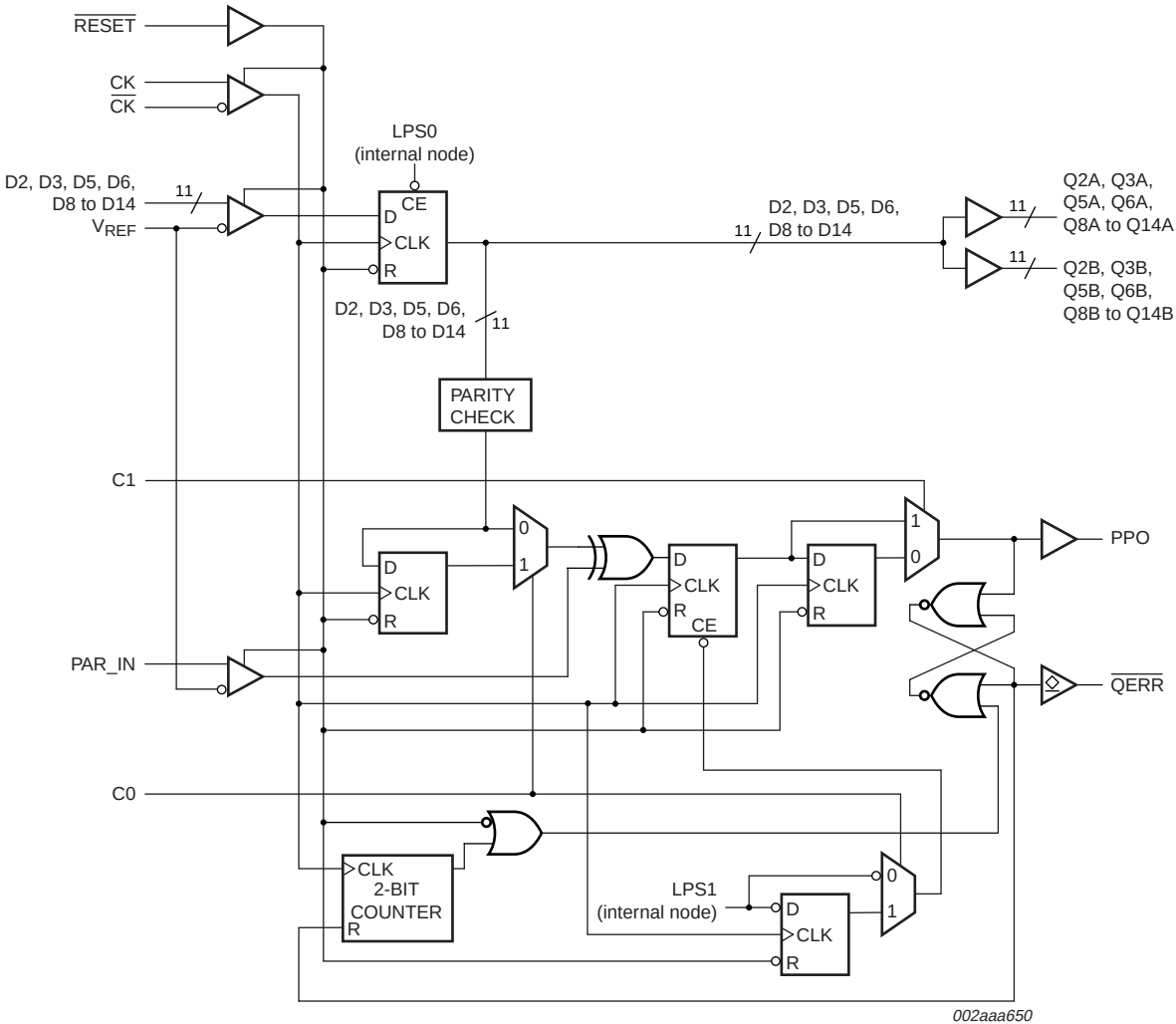


Fig 2. Parity logic diagram for 1:2 Register A configuration (positive logic); C0 = 0, C1 = 1

6. Pinning information

6.1 Pinning

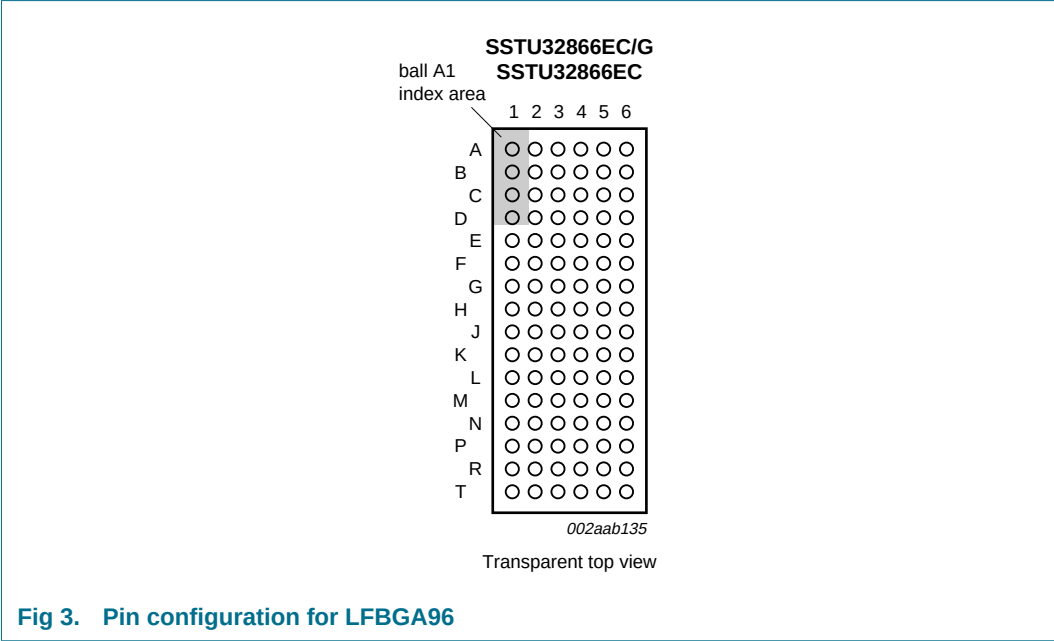


Fig 3. Pin configuration for LFBGA96

|   | 1      | 2     | 3    | 4   | 5    | 6      |
|---|--------|-------|------|-----|------|--------|
| A | DCKE   | PPO   | VREF | VDD | QCKE | d.n.u. |
| B | D2     | D15   | GND  | GND | Q2   | Q15    |
| C | D3     | D16   | VDD  | VDD | Q3   | Q16    |
| D | D0DT   | QERR  | GND  | GND | Q0DT | d.n.u. |
| E | D5     | D17   | VDD  | VDD | Q5   | Q17    |
| F | D6     | D18   | GND  | GND | Q6   | Q18    |
| G | PAR_IN | RESET | VDD  | VDD | C1   | C0     |
| H | CK     | DCS   | GND  | GND | QCS  | d.n.u. |
| J | CK     | CSR   | VDD  | VDD | n.c. | n.c.   |
| K | D8     | D19   | GND  | GND | Q8   | Q19    |
| L | D9     | D20   | VDD  | VDD | Q9   | Q20    |
| M | D10    | D21   | GND  | GND | Q10  | Q21    |
| N | D11    | D22   | VDD  | VDD | Q11  | Q22    |
| P | D12    | D23   | GND  | GND | Q12  | Q23    |
| R | D13    | D24   | VDD  | VDD | Q13  | Q24    |
| T | D14    | D25   | VREF | VDD | Q14  | Q25    |

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Fig 4. Ball mapping, 1:1 register (C0 = 0, C1 = 0)

|   | 1               | 2                  | 3                | 4               | 5                 | 6                 |
|---|-----------------|--------------------|------------------|-----------------|-------------------|-------------------|
| A | DCKE            | PPO                | V <sub>REF</sub> | V <sub>DD</sub> | QCKEA             | QCKEB             |
| B | D2              | d.n.u.             | GND              | GND             | Q2A               | Q2B               |
| C | D3              | d.n.u.             | V <sub>DD</sub>  | V <sub>DD</sub> | Q3A               | Q3B               |
| D | DODT            | $\overline{QERR}$  | GND              | GND             | QODTA             | QODTB             |
| E | D5              | n.c.               | V <sub>DD</sub>  | V <sub>DD</sub> | Q5A               | Q5B               |
| F | D6              | n.c.               | GND              | GND             | Q6A               | Q6B               |
| G | PAR_IN          | $\overline{RESET}$ | V <sub>DD</sub>  | V <sub>DD</sub> | C1                | C0                |
| H | CK              | $\overline{DCS}$   | GND              | GND             | $\overline{QCSA}$ | $\overline{QCSB}$ |
| J | $\overline{CK}$ | $\overline{CSR}$   | V <sub>DD</sub>  | V <sub>DD</sub> | n.c.              | n.c.              |
| K | D8              | d.n.u.             | GND              | GND             | Q8A               | Q8B               |
| L | D9              | d.n.u.             | V <sub>DD</sub>  | V <sub>DD</sub> | Q9A               | Q9B               |
| M | D10             | d.n.u.             | GND              | GND             | Q10A              | Q10B              |
| N | D11             | d.n.u.             | V <sub>DD</sub>  | V <sub>DD</sub> | Q11A              | Q11B              |
| P | D12             | d.n.u.             | GND              | GND             | Q12A              | Q12B              |
| R | D13             | d.n.u.             | V <sub>DD</sub>  | V <sub>DD</sub> | Q13A              | Q13B              |
| T | D14             | d.n.u.             | V <sub>REF</sub> | V <sub>DD</sub> | Q14A              | Q14B              |

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Fig 5. Ball mapping, 1:2 Register A (C0 = 0, C1 = 1)

|   | 1               | 2                  | 3                | 4               | 5                 | 6                 |
|---|-----------------|--------------------|------------------|-----------------|-------------------|-------------------|
| A | D1              | PPO                | V <sub>REF</sub> | V <sub>DD</sub> | Q1A               | Q1B               |
| B | D2              | d.n.u.             | GND              | GND             | Q2A               | Q2B               |
| C | D3              | d.n.u.             | V <sub>DD</sub>  | V <sub>DD</sub> | Q3A               | Q3B               |
| D | D4              | $\overline{QERR}$  | GND              | GND             | Q4A               | Q4B               |
| E | D5              | d.n.u.             | V <sub>DD</sub>  | V <sub>DD</sub> | Q5A               | Q5B               |
| F | D6              | d.n.u.             | GND              | GND             | Q6A               | Q6B               |
| G | PAR_IN          | $\overline{RESET}$ | V <sub>DD</sub>  | V <sub>DD</sub> | C1                | C0                |
| H | CK              | $\overline{DCS}$   | GND              | GND             | $\overline{QCSA}$ | $\overline{QCSB}$ |
| J | $\overline{CK}$ | $\overline{CSR}$   | V <sub>DD</sub>  | V <sub>DD</sub> | n.c.              | n.c.              |
| K | D8              | d.n.u.             | GND              | GND             | Q8A               | Q8B               |
| L | D9              | d.n.u.             | V <sub>DD</sub>  | V <sub>DD</sub> | Q9A               | Q9B               |
| M | D10             | d.n.u.             | GND              | GND             | Q10A              | Q10B              |
| N | DODT            | d.n.u.             | V <sub>DD</sub>  | V <sub>DD</sub> | QODTA             | QODTB             |
| P | D12             | d.n.u.             | GND              | GND             | Q12A              | Q12B              |
| R | D13             | d.n.u.             | V <sub>DD</sub>  | V <sub>DD</sub> | Q13A              | Q13B              |
| T | DCKE            | d.n.u.             | V <sub>REF</sub> | V <sub>DD</sub> | QCKEA             | QCKEB             |

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Fig 6. Ball mapping, 1:2 Register B (C0 = 1, C1 = 1)

## 6.2 Pin description

Table 2: Pin description

| Symbol                                                                           | Pin                                                                     | Type               | Description                                                                                                                |
|----------------------------------------------------------------------------------|-------------------------------------------------------------------------|--------------------|----------------------------------------------------------------------------------------------------------------------------|
| GND                                                                              | B3, B4, D3, D4,<br>F3, F4, H3, H4,<br>K3, K4, M3, M4,<br>P3, P4         | ground input       | ground                                                                                                                     |
| V <sub>DD</sub>                                                                  | A4, C3, C4, E3,<br>E4, G3, G4, J3,<br>J4, L3, L4, N3,<br>N4, R3, R4, T4 | 1.8 V nominal      | power supply voltage                                                                                                       |
| V <sub>REF</sub>                                                                 | A3, T3                                                                  | 0.9 V nominal      | input reference voltage                                                                                                    |
| CK                                                                               | H1                                                                      | Differential input | positive master clock input                                                                                                |
| $\overline{\text{CK}}$                                                           | J1                                                                      | Differential input | negative master clock input                                                                                                |
| C0                                                                               | G6                                                                      | LVCMOS inputs      | Configuration control inputs; Register A or Register B and 1:1 mode or 1:2 mode select.                                    |
| C1                                                                               | G5                                                                      |                    |                                                                                                                            |
| $\overline{\text{RESET}}$                                                        | G2                                                                      | LVCMOS input       | Asynchronous reset input. Resets registers and disables V <sub>REF</sub> data and clock.                                   |
| $\overline{\text{CSR}}$                                                          | J2                                                                      | SSTL_18 input      | Chip select inputs. Disables D1 to D25 <a href="#">[2]</a> outputs switching when both inputs are HIGH.                    |
| $\overline{\text{DCS}}$                                                          | H2                                                                      |                    |                                                                                                                            |
| D1 to D25                                                                        | <a href="#">[1]</a>                                                     | SSTL_18 input      | Data input. Clocked in on the crossing of the rising edge of CK and the falling edge of CK.                                |
| DODT                                                                             | <a href="#">[1]</a>                                                     | SSTL_18 input      | The outputs of this register bit will not be suspended by the $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ control. |
| DCKE                                                                             | <a href="#">[1]</a>                                                     | SSTL_18 input      | The outputs of this register bit will not be suspended by the $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ control. |
| PAR_IN                                                                           | G1                                                                      | SSTL_18 input      | Parity input. Arrives one clock cycle after the corresponding data input.                                                  |
| Q1 to Q25,<br>Q2A to Q14A,<br>Q1B to Q14B                                        | <a href="#">[1]</a>                                                     | 1.8 V CMOS outputs | Data outputs that are suspended by the $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ control. <a href="#">[3]</a>    |
| PPO                                                                              | A2                                                                      | 1.8 V CMOS output  | Partial parity out. Indicates odd parity of inputs D1 to D25 <a href="#">[2]</a> .                                         |
| $\overline{\text{QCS}}$ , $\overline{\text{QCSA}}$ ,<br>$\overline{\text{QCSB}}$ | <a href="#">[1]</a>                                                     | 1.8 V CMOS output  | Data output that will not be suspended by the $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ control.                 |
| QODT, QODTA,<br>QODTB                                                            | <a href="#">[1]</a>                                                     | 1.8 V CMOS output  | Data output that will not be suspended by the $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ control.                 |
| QCKE, QCKEA,<br>QCKEB                                                            | <a href="#">[1]</a>                                                     | 1.8 V CMOS output  | Data output that will not be suspended by the $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ control.                 |

Table 2: Pin description ...continued

| Symbol            | Pin | Type              | Description                                                                     |
|-------------------|-----|-------------------|---------------------------------------------------------------------------------|
| $\overline{QERR}$ | D2  | open-drain output | Output error bit. Generated one clock cycle after the corresponding data output |
| n.c.              | [1] | -                 | Not connected. Ball present but no internal connection to the die.              |
| d.n.u.            | [1] | -                 | Do not use. Inputs are in standby-equivalent mode and outputs are driven LOW.   |

[1] Depends on configuration. Refer to [Figure 4](#), [Figure 5](#), and [Figure 6](#) for ball number.

[2] Data inputs = D2, D3, D5, D6, D8 to D25 when C0 = 0 and C1 = 0.  
 Data inputs = D2, D3, D5, D6, D8 to D14 when C0 = 0 and C1 = 1.  
 Data inputs = D1 to D6, D8 to D10, D12, D13 when C0 = 1 and C1 = 1.

[3] Data outputs = Q2, Q3, Q5, Q6, Q8 to Q25 when C0 = 0 and C1 = 0.  
 Data outputs = Q2, Q3, Q5, Q6, Q8 to Q14 when C0 = 0 and C1 = 1.  
 Data outputs = Q1 to Q6, Q8 to Q10, Q12, Q13 when C0 = 1 and C1 = 1.

## 7. Functional description

The SSTU32866 is a 25-bit 1:1 or 14-bit 1:2 configurable registered buffer with parity, designed for 1.7 V to 1.9 V  $V_{DD}$  operation.

All clock and data inputs are compatible with the JEDEC standard for SSTL\_18. The control and reset ( $\overline{RESET}$ ) inputs are LVCMOS. All data outputs are 1.8 V CMOS drivers that have been optimized to drive the DDR2 DIMM load, and meet SSTL\_18 specifications. The error ( $\overline{QERR}$ ) output is 1.8 V open-drain driver.

The SSTU32866 operates from a differential clock (CK and  $\overline{CK}$ ). Data are registered at the crossing of CK going HIGH, and CK going LOW.

The C0 input controls the pinout configuration for the 1:2 pinout from A configuration (when LOW) to B configuration (when HIGH). The C1 input controls the pinout configuration from 25-bit 1:1 (when LOW) to 14-bit 1:2 (when HIGH).

The SSTU32866 accepts a parity bit from the memory controller on its parity bit (PAR\_IN) input, compares it with the data received on the DIMM-independent D-inputs and indicates whether a parity error has occurred on its open-drain  $\overline{QERR}$  pin (active-LOW). The convention is even parity, i.e., valid parity is defined as an even number of ones across the DIMM-independent data inputs combined with the parity input bit.

When used as a single device, the C0 and C1 inputs are tied LOW. In this configuration, parity is checked on the PAR\_IN input which arrives one cycle after the input data to which it applies. The partial-parity-out (PPO) and  $\overline{QERR}$  signals are produced three cycles after the corresponding data inputs.

When used in pairs, the C0 input of the first register is tied LOW and the C0 input of the second register is tied HIGH. The C1 input of both registers are tied HIGH. Parity, which arrives one cycle after the data input to which it applies, is checked on the PAR\_IN input of the first device. The PPO and  $\overline{QERR}$  signals are produced on the second device three clock cycles after the corresponding data inputs. The PPO output of the first register is



cascaded to the PAR\_IN of the second register. The  $\overline{QERR}$  output of the first register is left floating and the valid error information is latched on the  $\overline{QERR}$  output of the second register.

If an error occurs and the  $\overline{QERR}$  output is driven LOW, it stays latched LOW for two clock cycles or until  $\overline{RESET}$  is driven LOW. The DIMM-dependent signals ( $\overline{DCKE}$ ,  $\overline{DCS}$ ,  $\overline{DODT}$ , and  $\overline{CSR}$ ) are not included in the parity check computation.

The device supports low-power standby operation. When  $\overline{RESET}$  is LOW, the differential input receivers are disabled, and undriven (floating) data, clock and reference voltage ( $V_{REF}$ ) inputs are allowed. In addition, when  $\overline{RESET}$  is LOW all registers are reset, and all outputs are forced LOW. The LVC MOS  $\overline{RESET}$  input must always be held at a valid logic HIGH or LOW level.

The device also supports low-power active operation by monitoring both system chip select ( $\overline{DCS}$  and  $\overline{CSR}$ ) inputs and will gate the Qn and PPO outputs from changing states when both  $\overline{DCS}$  and  $\overline{CSR}$  inputs are HIGH. If either  $\overline{DCS}$  or  $\overline{CSR}$  input is LOW, the Qn and PPO outputs will function normally. The  $\overline{RESET}$  input has priority over the  $\overline{DCS}$  and  $\overline{CSR}$  control and when driven LOW will force the Qn and PPO outputs LOW, and the  $\overline{QERR}$  output HIGH. If the  $\overline{DCS}$  control functionality is not desired, then the  $\overline{CSR}$  input can be hard-wired to ground, in which case, the set-up time requirement for  $\overline{DCS}$  would be the same as for the other Dn data inputs. To control the low-power mode with  $\overline{DCS}$  only, then the  $\overline{CSR}$  input should be pulled up to  $V_{DD}$  through a pull-up resistor.

To ensure defined outputs from the register before a stable clock has been supplied,  $\overline{RESET}$  must be held in the LOW state during power-up.

In the DDR2 RDIMM application,  $\overline{RESET}$  is specified to be completely asynchronous with respect to CK and  $\overline{CK}$ . Therefore, no timing relationship can be guaranteed between the two. When entering reset, the register will be cleared and the Qn outputs will be driven LOW quickly, relative to the time to disable the differential input receivers. However, when coming out of reset, the register will become active quickly, relative to the time to enable the differential input receivers. As long as the data inputs are LOW, and the clock is stable during the time from the LOW-to-HIGH transition of  $\overline{RESET}$  until the input receivers are fully enabled, the design of the SSTU32866 must ensure that the outputs will remain LOW, thus ensuring no glitches on the output.

## 7.1 Function table

**Table 3: Function table (each flip-flop)**

L = LOW voltage level; H = HIGH voltage level; X = don't care; ↑ = LOW-to-HIGH transition; ↓ = HIGH-to-LOW transition

| Inputs |               |               |               |               |                  | Outputs <sup>[1]</sup> |                |                |
|--------|---------------|---------------|---------------|---------------|------------------|------------------------|----------------|----------------|
| RESET  | DCS           | CSR           | CK            | CK̄           | Dn, DODTn, DCKEn | Qn                     | QCS            | QODT, QCKE     |
| H      | L             | L             | ↑             | ↓             | L                | L                      | L              | L              |
| H      | L             | L             | ↑             | ↓             | H                | H                      | L              | H              |
| H      | L             | L             | L or H        | L or H        | X                | Q <sub>0</sub>         | Q <sub>0</sub> | Q <sub>0</sub> |
| H      | L             | H             | ↑             | ↓             | L                | L                      | L              | L              |
| H      | L             | H             | ↑             | ↓             | H                | H                      | L              | H              |
| H      | L             | H             | L or H        | L or H        | X                | Q <sub>0</sub>         | Q <sub>0</sub> | Q <sub>0</sub> |
| H      | H             | L             | ↑             | ↓             | L                | L                      | H              | L              |
| H      | H             | L             | ↑             | ↓             | H                | H                      | H              | H              |
| H      | H             | L             | L or H        | L or H        | X                | Q <sub>0</sub>         | Q <sub>0</sub> | Q <sub>0</sub> |
| H      | H             | H             | ↑             | ↓             | L                | Q <sub>0</sub>         | H              | L              |
| H      | H             | H             | ↑             | ↓             | H                | Q <sub>0</sub>         | H              | H              |
| H      | H             | H             | L or H        | L or H        | X                | Q <sub>0</sub>         | Q <sub>0</sub> | Q <sub>0</sub> |
| L      | X or floating | X or floating | X or floating | X or floating | X or floating    | L                      | L              | L              |

[1] Q<sub>0</sub> is the previous state of the associated output.

**Table 4: Parity and standby function table**

L = LOW voltage level; H = HIGH voltage level; X = don't care; ↑ = LOW-to-HIGH transition; ↓ = HIGH-to-LOW transition

| Inputs |               |               |               |               |                             |                       | Outputs <sup>[1]</sup> |                   |
|--------|---------------|---------------|---------------|---------------|-----------------------------|-----------------------|------------------------|-------------------|
| RESET  | DCS           | CSR           | CK            | CK̄           | Σ of inputs = H (D1 to D25) | PAR_IN <sup>[2]</sup> | PPO <sup>[3]</sup>     | QERR              |
| H      | L             | X             | ↑             | ↓             | even                        | L                     | L                      | H                 |
| H      | L             | X             | ↑             | ↓             | odd                         | L                     | H                      | L                 |
| H      | L             | X             | ↑             | ↓             | even                        | H                     | H                      | L                 |
| H      | L             | X             | ↑             | ↓             | odd                         | H                     | L                      | H                 |
| H      | H             | L             | ↑             | ↓             | even                        | L                     | L                      | H                 |
| H      | H             | L             | ↑             | ↓             | odd                         | L                     | H                      | L                 |
| H      | H             | L             | ↑             | ↓             | even                        | H                     | H                      | L                 |
| H      | H             | L             | ↑             | ↓             | odd                         | H                     | L                      | H                 |
| H      | H             | H             | ↑             | ↓             | X                           | X                     | PPO <sub>0</sub>       | QERR <sub>0</sub> |
| H      | X             | X             | L or H        | L or H        | X                           | X                     | PPO <sub>0</sub>       | QERR <sub>0</sub> |
| L      | X or floating | X or floating | X or floating | X or floating | X or floating               | X or floating         | L                      | H                 |

[1] PPO<sub>0</sub> is the previous state of output PPO; QERR<sub>0</sub> is the previous state of output QERR.

[2] Data inputs = D2, D3, D5, D6, D8 to D25 when C0 = 0 and C1 = 0.

Data inputs = D2, D3, D5, D6, D8 to D14 when C0 = 0 and C1 = 1.

Data inputs = D1 to D6, D8 to D10, D12, D13 when C0 = 1 and C1 = 1.

[3] PAR\_IN arrives one clock cycle (C0 = 0), or two clock cycles (C0 = 1), after the data to which it applies.

[4] This condition assumes QERR is HIGH at the crossing of CK going HIGH and CK̄ going LOW. If QERR is LOW, it stays latched LOW for two clock cycles or until RESET is driven LOW.

## 8. Limiting values

**Table 5: Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). [\[1\]](#)

| Symbol    | Parameter                                           | Conditions                             | Min                      | Max                                | Unit |
|-----------|-----------------------------------------------------|----------------------------------------|--------------------------|------------------------------------|------|
| $V_{DD}$  | supply voltage                                      |                                        | −0.5                     | +2.5                               | V    |
| $V_I$     | receiver input voltage                              |                                        | −0.5 <a href="#">[2]</a> | +2.5 <a href="#">[3]</a>           | V    |
| $V_O$     | driver output voltage                               |                                        | −0.5 <a href="#">[2]</a> | $V_{DD} + 0.5$ <a href="#">[3]</a> | V    |
| $I_{IK}$  | input clamp current                                 | $V_I < 0$ V or $V_I > V_{DD}$          | -                        | −50                                | mA   |
| $I_{OK}$  | output clamp current                                | $V_O < 0$ V or $V_O > V_{DD}$          | -                        | ±50                                | mA   |
| $I_O$     | continuous output current                           | $0$ V < $V_O < V_{DD}$                 | -                        | ±50                                | mA   |
| $I_{CCC}$ | continuous current through each $V_{DD}$ or GND pin |                                        | -                        | ±100                               | mA   |
| $T_{stg}$ | storage temperature                                 |                                        | −65                      | +150                               | °C   |
| $V_{esd}$ | electrostatic discharge voltage                     | Human Body Model (HBM); 1.5 kΩ; 100 pF | 2                        | -                                  | kV   |
|           |                                                     | Machine Model (MM); 0 Ω; 200 pF        | 200                      | -                                  | V    |

[1] Stresses beyond those listed under 'absolute maximum ratings' may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under 'recommended operating conditions' is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[2] The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

[3] This value is limited to 2.5 V maximum.

## 9. Recommended operating conditions

**Table 6: Recommended operating conditions**

| Symbol       | Parameter                       | Conditions                                      | Min                  | Typ                  | Max                  | Unit |
|--------------|---------------------------------|-------------------------------------------------|----------------------|----------------------|----------------------|------|
| $V_{DD}$     | supply voltage                  |                                                 | 1.7                  | -                    | 1.9                  | V    |
| $V_{REF}$    | reference voltage               |                                                 | $0.49 \times V_{DD}$ | $0.50 \times V_{DD}$ | $0.51 \times V_{DD}$ | V    |
| $V_{TT}$     | termination voltage             |                                                 | $V_{REF} - 40$ mV    | $V_{REF}$            | $V_{REF} + 40$ mV    | V    |
| $V_I$        | input voltage                   |                                                 | 0                    | -                    | $V_{DD}$             | V    |
| $V_{IH(AC)}$ | AC HIGH-level input voltage     | data (Dn), $\overline{CSR}$ , and PAR_IN inputs | $V_{REF} + 250$ mV   | -                    | -                    | V    |
| $V_{IL(AC)}$ | AC LOW-level input voltage      | data (Dn), $\overline{CSR}$ , and PAR_IN inputs | -                    | -                    | $V_{REF} - 250$ mV   | V    |
| $V_{IH(DC)}$ | DC HIGH-level input voltage     | data (Dn), $\overline{CSR}$ , and PAR_IN inputs | $V_{REF} + 125$ mV   | -                    | -                    | V    |
| $V_{IL(DC)}$ | DC LOW-level input voltage      | data (Dn), $\overline{CSR}$ , and PAR_IN inputs | -                    | -                    | $V_{REF} - 125$ mV   | V    |
| $V_{IH}$     | HIGH-level input voltage        | $\overline{RESET}$ , Cn <a href="#">[1]</a>     | $0.65 \times V_{DD}$ | -                    | -                    | V    |
| $V_{IL}$     | LOW-level input voltage         | $\overline{RESET}$ , Cn <a href="#">[1]</a>     | -                    | -                    | $0.35 \times V_{DD}$ | V    |
| $V_{ICR}$    | common mode input voltage range | CK, $\overline{CK}$ <a href="#">[2]</a>         | 0.675                | -                    | 1.125                | V    |

Table 6: Recommended operating conditions ...continued

| Symbol           | Parameter                                 | Conditions                 | Min     | Typ | Max | Unit |
|------------------|-------------------------------------------|----------------------------|---------|-----|-----|------|
| V <sub>ID</sub>  | differential input voltage                | CK, $\overline{\text{CK}}$ | [2] 600 | -   | -   | mV   |
| I <sub>OH</sub>  | HIGH-level output current                 |                            | -       | -   | -8  | mA   |
| I <sub>OL</sub>  | LOW-level output current                  |                            | -       | -   | 8   | mA   |
| T <sub>amb</sub> | operating ambient temperature in free air |                            | 0       | -   | +70 | °C   |

[1] The  $\overline{\text{RESET}}$  and Cn inputs of the device must be held at valid levels (not floating) to ensure proper device operation.

[2] The differential inputs must not be floating, unless  $\overline{\text{RESET}}$  is LOW.

## 10. Characteristics

Table 7: Characteristics

At recommended operating conditions (see Table 6), unless otherwise specified.

| Symbol           | Parameter                                                        | Conditions                                                                                                                                                                                                                                                                                | Min | Typ | Max | Unit |
|------------------|------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|-----|-----|------|
| V <sub>OH</sub>  | HIGH-level output voltage                                        | I <sub>OH</sub> = -6 mA; V <sub>DD</sub> = 1.7 V                                                                                                                                                                                                                                          | 1.2 | -   | -   | V    |
| V <sub>OL</sub>  | LOW-level output voltage                                         | I <sub>OL</sub> = 6 mA; V <sub>DD</sub> = 1.7 V                                                                                                                                                                                                                                           | -   | -   | 0.5 | V    |
| I <sub>I</sub>   | input current                                                    | all inputs; V <sub>I</sub> = V <sub>DD</sub> or GND; V <sub>DD</sub> = 1.9 V                                                                                                                                                                                                              | -   | -   | ±5  | μA   |
| I <sub>DD</sub>  | static standby current                                           | $\overline{\text{RESET}}$ = GND; I <sub>O</sub> = 0 mA; V <sub>DD</sub> = 1.9 V                                                                                                                                                                                                           | -   | -   | 100 | μA   |
|                  | static operating current                                         | $\overline{\text{RESET}}$ = V <sub>DD</sub> ; I <sub>O</sub> = 0 mA; V <sub>DD</sub> = 1.9 V; V <sub>I</sub> = V <sub>IH(AC)</sub> or V <sub>IL(AC)</sub>                                                                                                                                 | -   | -   | 40  | mA   |
| I <sub>DDD</sub> | dynamic operating current per MHz, clock only                    | $\overline{\text{RESET}}$ = V <sub>DD</sub> ; V <sub>I</sub> = V <sub>IH(AC)</sub> or V <sub>IL(AC)</sub> ; CK and $\overline{\text{CK}}$ switching at 50 % duty cycle. I <sub>O</sub> = 0 mA; V <sub>DD</sub> = 1.8 V                                                                    | -   | 16  | -   | μA   |
|                  | dynamic operating current per MHz, per each data input, 1:1 mode | $\overline{\text{RESET}}$ = V <sub>DD</sub> ; V <sub>I</sub> = V <sub>IH(AC)</sub> or V <sub>IL(AC)</sub> ; CK and $\overline{\text{CK}}$ switching at 50 % duty cycle. One data input switching at half clock frequency, 50 % duty cycle. I <sub>O</sub> = 0 mA; V <sub>DD</sub> = 1.8 V | -   | 11  | -   | μA   |
|                  | dynamic operating current per MHz, per each data input, 1:2 mode | $\overline{\text{RESET}}$ = V <sub>DD</sub> ; V <sub>I</sub> = V <sub>IH(AC)</sub> or V <sub>IL(AC)</sub> ; CK and $\overline{\text{CK}}$ switching at 50 % duty cycle. One data input switching at half clock frequency, 50 % duty cycle. I <sub>O</sub> = 0 mA; V <sub>DD</sub> = 1.8 V | -   | 19  | -   | μA   |
| C <sub>i</sub>   | input capacitance, data and $\overline{\text{CSR}}$ inputs       | V <sub>I</sub> = V <sub>REF</sub> ± 250 mV; V <sub>DD</sub> = 1.8 V                                                                                                                                                                                                                       | 2.5 | -   | 3.5 | pF   |
|                  | input capacitance, CK and $\overline{\text{CK}}$ inputs          | V <sub>ICR</sub> = 0.9 V; V <sub>i(p-p)</sub> = 600 mV; V <sub>DD</sub> = 1.8 V                                                                                                                                                                                                           | 2   | -   | 3   | pF   |
|                  | input capacitance, $\overline{\text{RESET}}$ input               | V <sub>I</sub> = V <sub>DD</sub> or GND; V <sub>DD</sub> = 1.8 V                                                                                                                                                                                                                          | 3   | -   | 4   | pF   |

**Table 8: Timing requirements**At recommended operating conditions (see [Table 6](#)), unless otherwise specified. See [Figure 2](#).

| Symbol             | Parameter                                              | Conditions                                                                                                                                                                                                       | Min     | Typ | Max | Unit |
|--------------------|--------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------|-----|-----|------|
| $f_{\text{clock}}$ | clock frequency                                        |                                                                                                                                                                                                                  | -       | -   | 450 | MHz  |
| $t_{\text{W}}$     | pulse duration, CK, $\overline{\text{CK}}$ HIGH or LOW |                                                                                                                                                                                                                  | 1       | -   | -   | ns   |
| $t_{\text{ACT}}$   | differential inputs active time                        |                                                                                                                                                                                                                  | [1] [2] | -   | 10  | ns   |
| $t_{\text{INACT}}$ | differential inputs inactive time                      |                                                                                                                                                                                                                  | [1] [3] | -   | 15  | ns   |
| $t_{\text{SU}}$    | set-up time                                            | DCS before CK $\uparrow$ , $\overline{\text{CK}}$ $\downarrow$ , $\overline{\text{CSR}}$ HIGH; $\overline{\text{CSR}}$ before CK $\uparrow$ , $\overline{\text{CK}}$ $\downarrow$ , $\overline{\text{DCS}}$ HIGH | 0.7     | -   | -   | ns   |
|                    |                                                        | $\overline{\text{DCS}}$ before CK $\uparrow$ , $\overline{\text{CK}}$ $\downarrow$ , $\overline{\text{CSR}}$ LOW                                                                                                 | 0.5     | -   | -   | ns   |
|                    |                                                        | DODT, DCKE and data (Dn) before CK $\uparrow$ , $\overline{\text{CK}}$ $\downarrow$                                                                                                                              | 0.5     | -   | -   | ns   |
|                    |                                                        | PAR_IN before CK $\uparrow$ , $\overline{\text{CK}}$ $\downarrow$                                                                                                                                                | 0.5     | -   | -   | ns   |
| $t_{\text{H}}$     | hold time                                              | DCS, DODT, DCKE and data (Dn) after CK $\uparrow$ , $\overline{\text{CK}}$ $\downarrow$                                                                                                                          | 0.5     | -   | -   | ns   |
|                    |                                                        | PAR_IN after CK $\uparrow$ , $\overline{\text{CK}}$ $\downarrow$                                                                                                                                                 | 0.5     | -   | -   | ns   |

[1] This parameter is not necessarily production tested.

[2]  $V_{\text{REF}}$  must be held at a valid input voltage level and data inputs must be held LOW for a minimum time of  $t_{\text{ACT(max)}}$  after  $\overline{\text{RESET}}$  is taken HIGH.[3]  $V_{\text{REF}}$ , data and clock inputs must be held at valid levels (not floating) a minimum time of  $t_{\text{INACT(max)}}$  after  $\overline{\text{RESET}}$  is taken LOW.**Table 9: Switching characteristics**At recommended operating conditions (see [Table 6](#)), unless otherwise specified. See [Section 11.1](#).

| Symbol             | Parameter                                 | Conditions                                                                             | Min     | Typ  | Max | Unit   |
|--------------------|-------------------------------------------|----------------------------------------------------------------------------------------|---------|------|-----|--------|
| $f_{\text{MAX}}$   | maximum input clock frequency             |                                                                                        | 450     | -    | -   | MHz    |
| $t_{\text{PDM}}$   | propagation delay, single bit switching   | from CK $\uparrow$ and $\overline{\text{CK}}$ $\downarrow$ to Qn                       | [1]     | 1.41 | -   | 1.8 ns |
| $t_{\text{PD}}$    | propagation delay                         | from CK $\uparrow$ and $\overline{\text{CK}}$ $\downarrow$ to PPO                      | 0.5     | -    | 1.8 | ns     |
| $t_{\text{LH}}$    | LOW-to-HIGH propagation delay             | from CK $\uparrow$ and $\overline{\text{CK}}$ $\downarrow$ to $\overline{\text{QERR}}$ | 1.2     | -    | 3   | ns     |
| $t_{\text{HL}}$    | HIGH-to-LOW propagation delay             | from CK $\uparrow$ and $\overline{\text{CK}}$ $\downarrow$ to $\overline{\text{QERR}}$ | 1       | -    | 2.4 | ns     |
| $t_{\text{PDMSS}}$ | propagation delay, simultaneous switching | from CK $\uparrow$ and $\overline{\text{CK}}$ $\downarrow$ to Qn                       | [1] [2] | -    | 2.0 | ns     |
| $t_{\text{PHL}}$   | HIGH-to-LOW propagation delay             | from $\overline{\text{RESET}}$ $\downarrow$ to Qn $\downarrow$                         | -       | -    | 3   | ns     |
|                    |                                           | from $\overline{\text{RESET}}$ $\downarrow$ to PPO $\downarrow$                        | -       | -    | 3   | ns     |
| $t_{\text{PLH}}$   | LOW-to-HIGH propagation delay             | from $\overline{\text{RESET}}$ $\downarrow$ to $\overline{\text{QERR}}$ $\uparrow$     | -       | -    | 3   | ns     |

[1] Includes 350 ps of test-load transmission line delay.

[2] This parameter is not necessarily production tested.

**Table 10: Data output edge rates**At recommended operating conditions (see [Table 6](#)), unless otherwise specified. See [Section 11.2](#).

| Symbol             | Parameter                                                             | Conditions                        | Min | Typ | Max | Unit |
|--------------------|-----------------------------------------------------------------------|-----------------------------------|-----|-----|-----|------|
| $dV/dt_{\text{r}}$ | rising edge slew rate                                                 | from 20 % to 80 %                 | 1   | -   | 4   | V/ns |
| $dV/dt_{\text{f}}$ | falling edge slew rate                                                | from 80 % to 20 %                 | 1   | -   | 4   | V/ns |
| $dV/dt_{\Delta}$   | absolute difference between $dV/dt_{\text{r}}$ and $dV/dt_{\text{f}}$ | from 20 % or 80 % to 80 % or 20 % | -   | -   | 1   | V/ns |



10.1 Timing diagrams

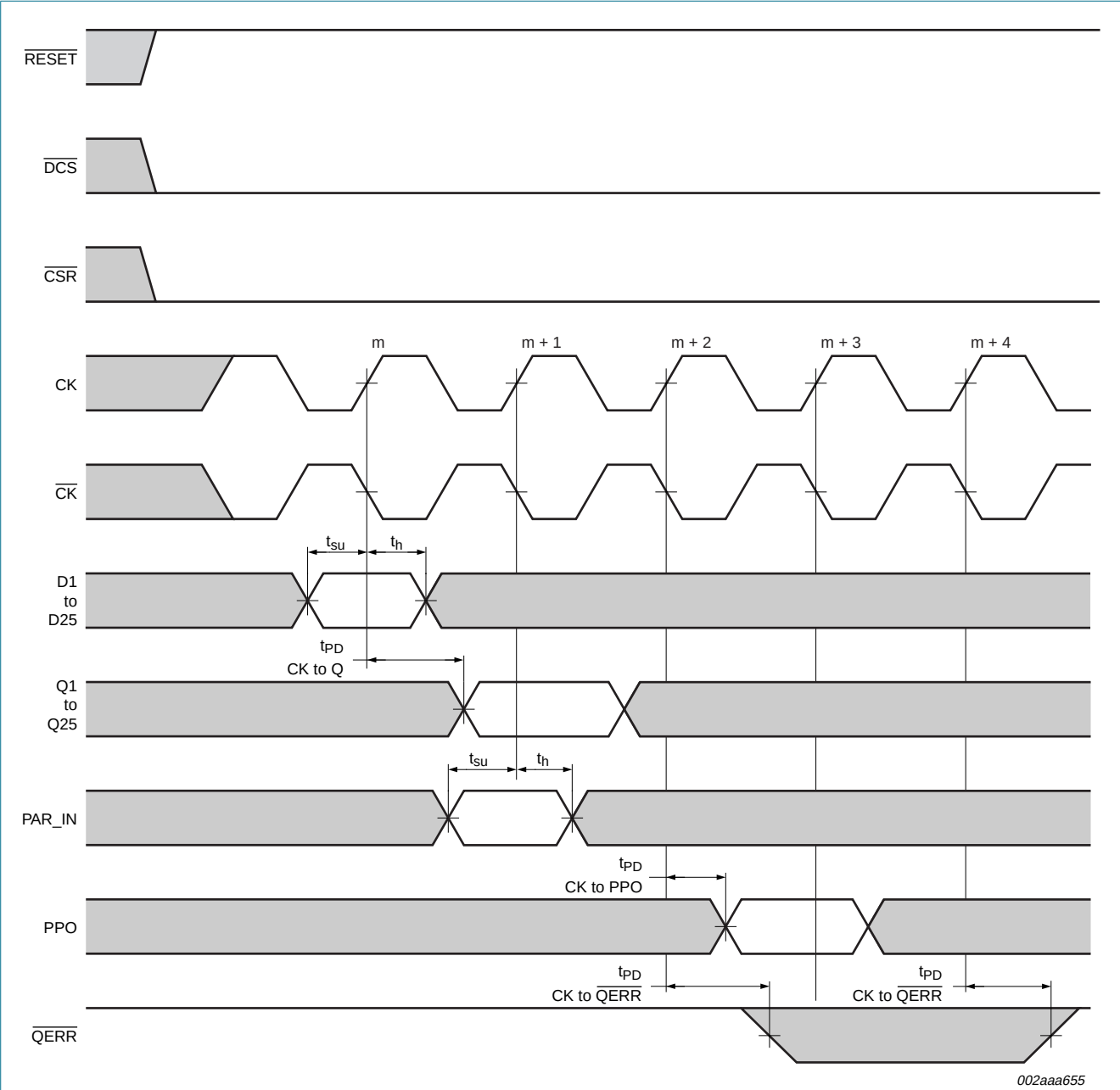
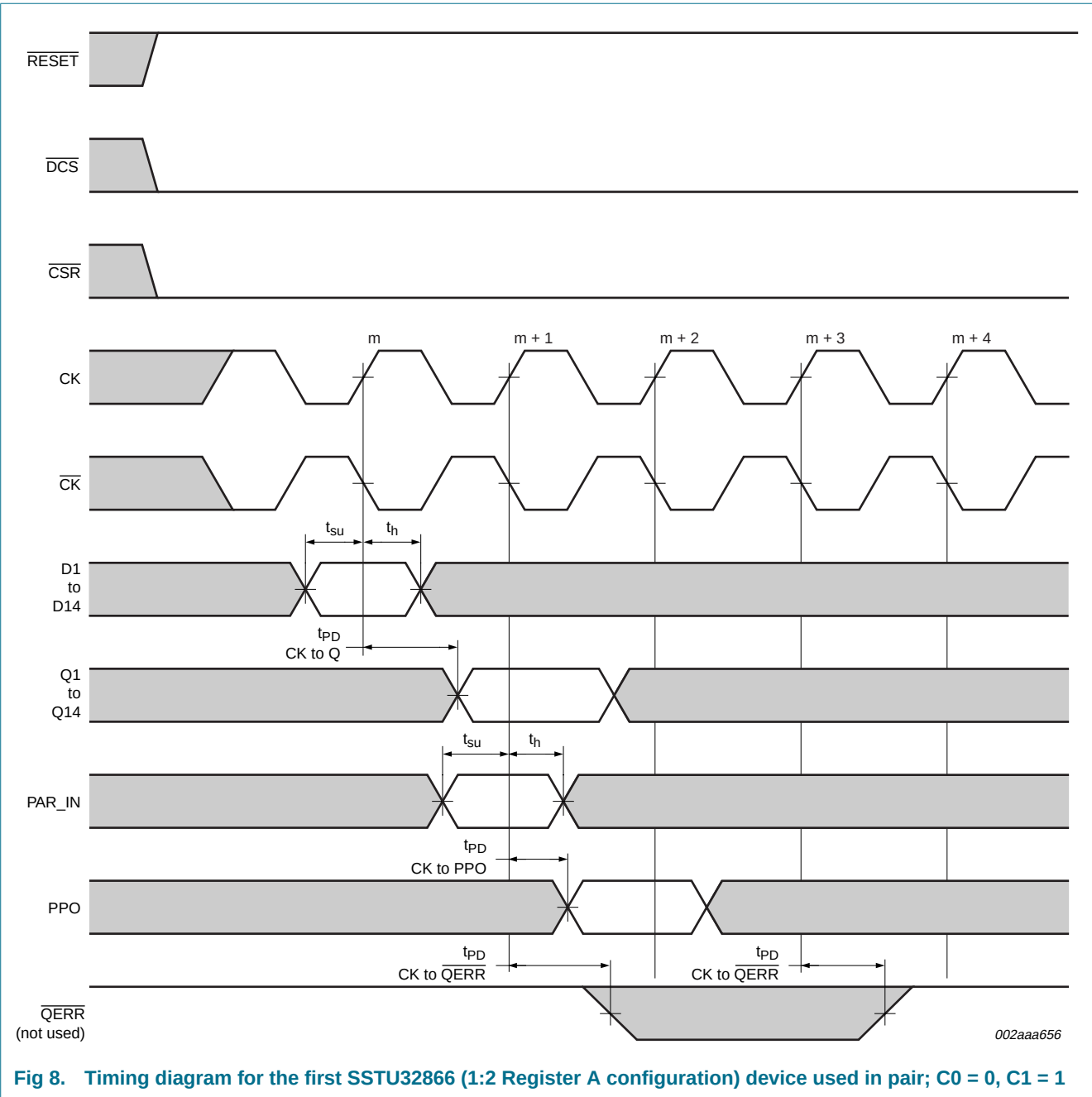
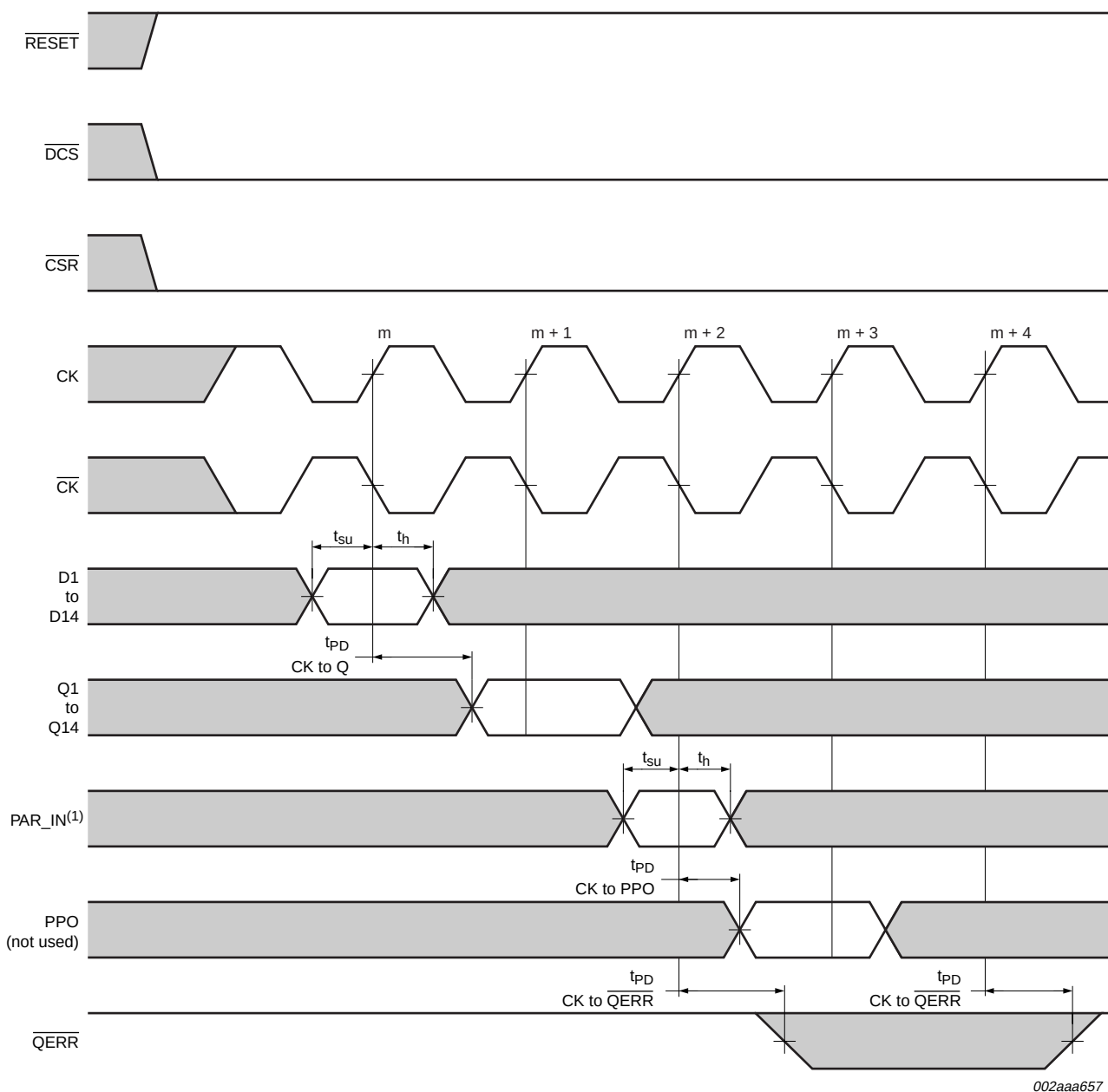


Fig 7. Timing diagram for SSTU32866 used as a single device; C0 = 0, C1 = 0





(1) PAR\_IN is driven from PPO of the first SSTU32866 device.

**Fig 9. Timing diagram for the second SSTU32866 (1:2 Register B configuration) device used in pair; C0 = 1, C1 = 1**



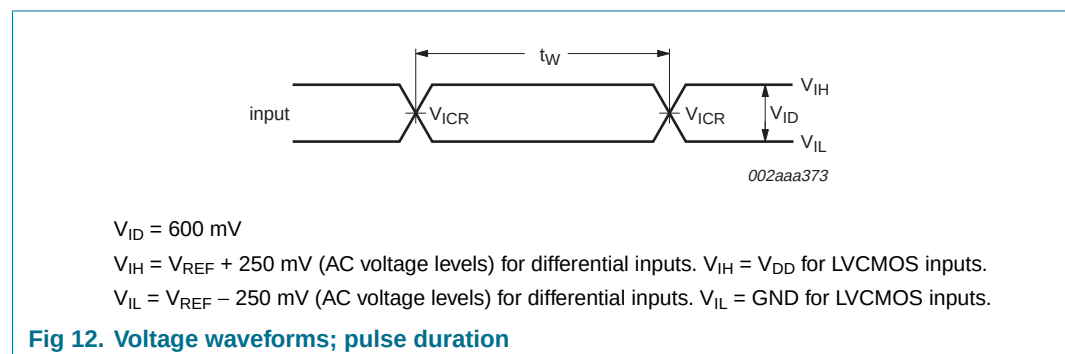
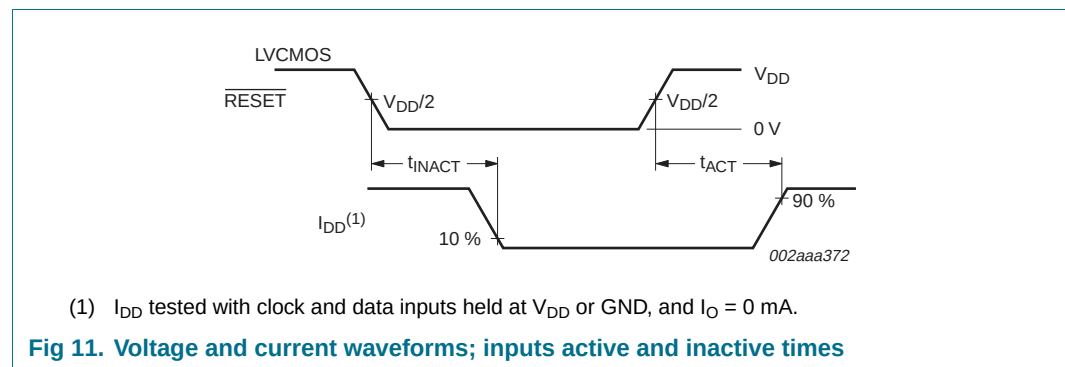
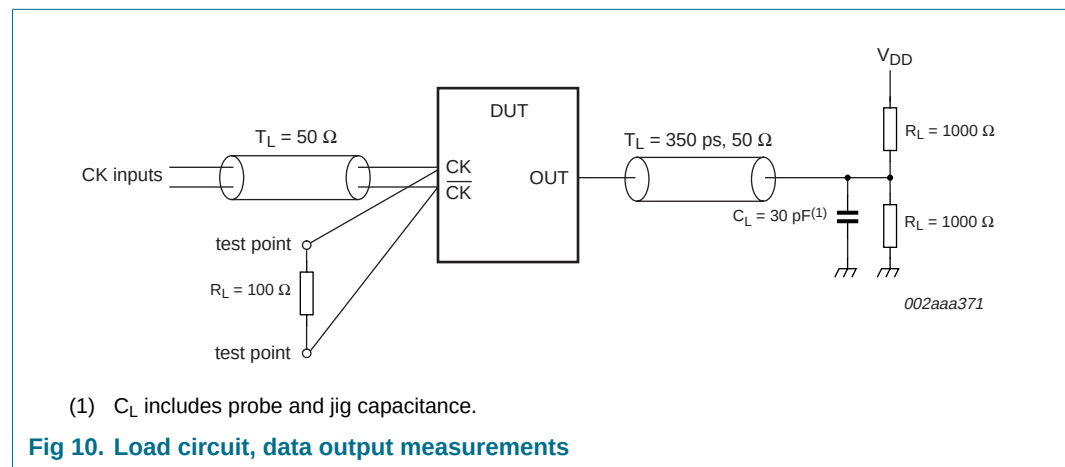
## 11. Test information

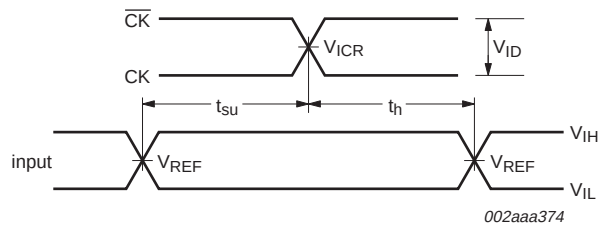
### 11.1 Parameter measurement information for data output load circuit

$V_{DD} = 1.8 \text{ V} \pm 0.1 \text{ V}$ .

All input pulses are supplied by generators having the following characteristics:  
 $PRR \leq 10 \text{ MHz}$ ;  $Z_0 = 50 \Omega$ ; input slew rate =  $1 \text{ V/ns} \pm 20 \%$ , unless otherwise specified.

The outputs are measured one at a time with one transition per measurement.





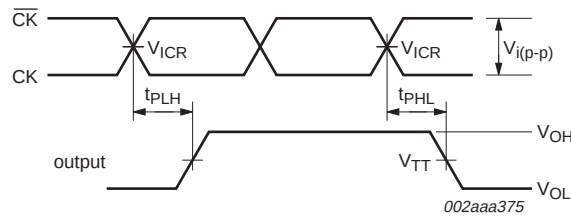
$$V_{ID} = 600 \text{ mV}$$

$$V_{REF} = V_{DD}/2$$

$V_{IH} = V_{REF} + 250 \text{ mV}$  (AC voltage levels) for differential inputs.  $V_{IH} = V_{DD}$  for LVCMOS inputs.

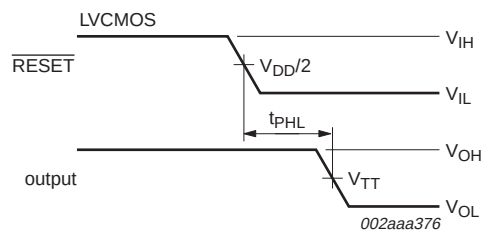
$V_{IL} = V_{REF} - 250 \text{ mV}$  (AC voltage levels) for differential inputs.  $V_{IL} = \text{GND}$  for LVCMOS inputs.

**Fig 13. Voltage waveforms; set-up and hold times**



$t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$ .

**Fig 14. Voltage waveforms; propagation delay times (clock to output)**



$t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$ .

$V_{IH} = V_{REF} + 250 \text{ mV}$  (AC voltage levels) for differential inputs.  $V_{IH} = V_{DD}$  for LVCMOS inputs.

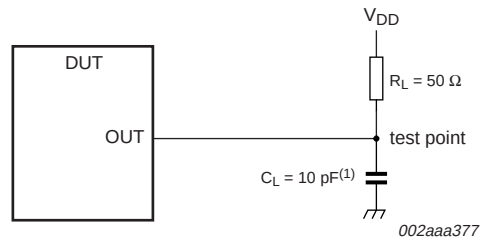
$V_{IL} = V_{REF} - 250 \text{ mV}$  (AC voltage levels) for differential inputs.  $V_{IL} = \text{GND}$  for LVCMOS inputs.

**Fig 15. Voltage waveforms; propagation delay times (reset to output)**

## 11.2 Data output slew rate measurement information

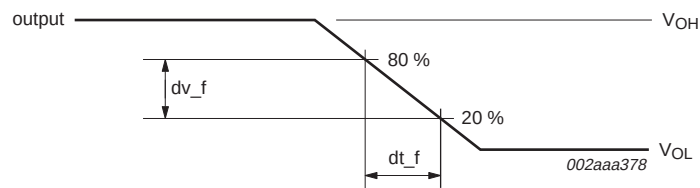
$$V_{DD} = 1.8 \text{ V} \pm 0.1 \text{ V.}$$

All input pulses are supplied by generators having the following characteristics:  
 $PRR \leq 10 \text{ MHz}$ ;  $Z_0 = 50 \Omega$ ; input slew rate =  $1 \text{ V/ns} \pm 20 \%$ , unless otherwise specified.

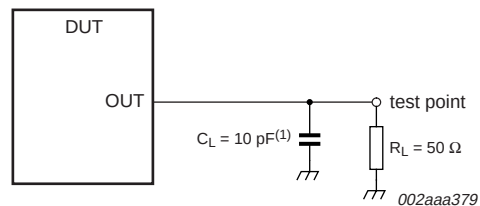


(1)  $C_L$  includes probe and jig capacitance.

**Fig 16. Load circuit, HIGH-to-LOW slew rate measurement**

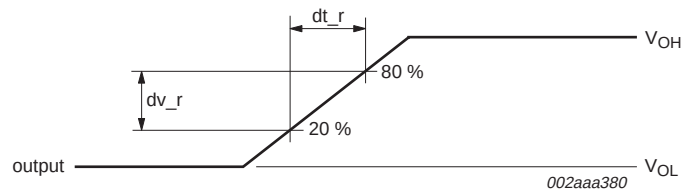


**Fig 17. Voltage waveforms, HIGH-to-LOW slew rate measurement**



(1)  $C_L$  includes probe and jig capacitance.

**Fig 18. Load circuit, LOW-to-HIGH slew rate measurement**

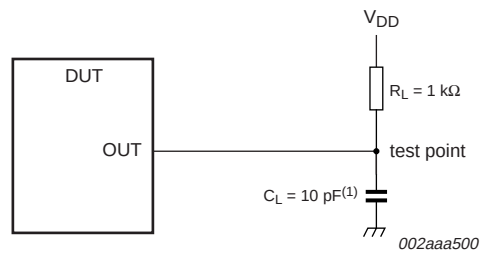


**Fig 19. Voltage waveforms, LOW-to-HIGH slew rate measurement**

### 11.3 Error output load circuit and voltage measurement information

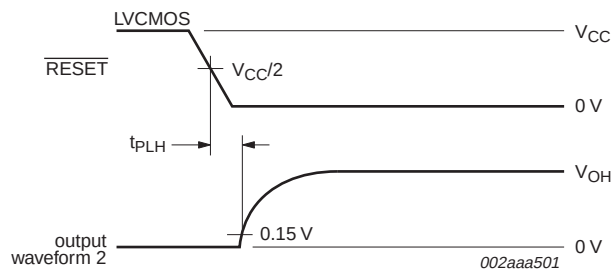
$V_{DD} = 1.8 \text{ V} \pm 0.1 \text{ V}$ .

All input pulses are supplied by generators having the following characteristics:  
 $PRR \leq 10 \text{ MHz}$ ;  $Z_0 = 50 \Omega$ ; input slew rate =  $1 \text{ V/ns} \pm 20 \%$ , unless otherwise specified.

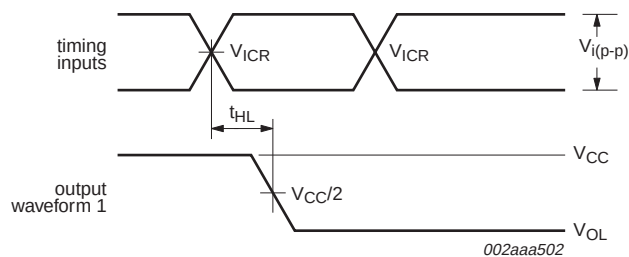


(1)  $C_L$  includes probe and jig capacitance.

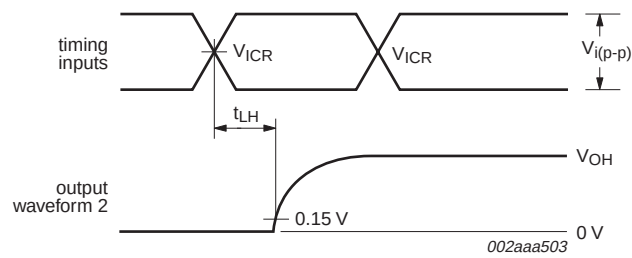
**Fig 20. Load circuit, error output measurements**



**Fig 21. Voltage waveforms, open-drain output LOW-to-HIGH transition time with respect to RESET input.**



**Fig 22. Voltage waveforms, open-drain output HIGH-to-LOW transition time with respect to clock inputs**

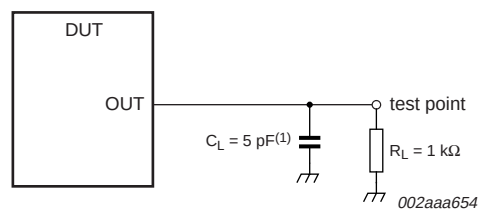


**Fig 23. Voltage waveforms, open-drain output LOW-to-HIGH transition time with respect to clock inputs**

#### 11.4 Partial Parity Out load circuit and voltage measurement information

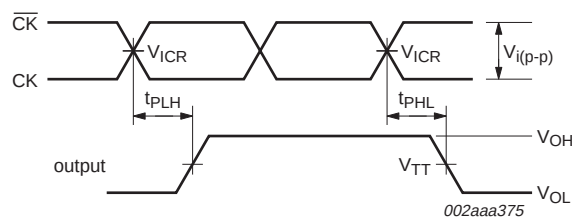
$$V_{DD} = 1.8 \text{ V} \pm 0.1 \text{ V.}$$

All input pulses are supplied by generators having the following characteristics:  
 $PRR \leq 10 \text{ MHz}$ ;  $Z_0 = 50 \Omega$ ; input slew rate =  $1 \text{ V/ns} \pm 20 \%$ , unless otherwise specified.



(1)  $C_L$  includes probe and jig capacitance.

**Fig 24. Partial Parity Out load circuit**

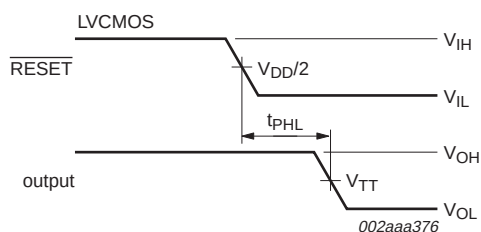


$$V_{TT} = V_{DD}/2$$

$t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$ .

$$V_{i(p-p)} = 600 \text{ mV}$$

**Fig 25. Partial Parity Out voltage waveforms; propagation delay times with respect to clock inputs**



$$V_{TT} = V_{DD}/2$$

$t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$ .

$V_{IH} = V_{REF} + 250 \text{ mV}$  (AC voltage levels) for differential inputs.  $V_{IH} = V_{DD}$  for LVC MOS inputs.

$V_{IL} = V_{REF} - 250 \text{ mV}$  (AC voltage levels) for differential inputs.  $V_{IL} = V_{DD}$  for LVC MOS inputs.

**Fig 26. Partial Parity Out voltage waveforms; propagation delay times with respect to RESET input**

12. Package outline

LFBGA96: plastic low profile fine-pitch ball grid array package; 96 balls; body 13.5 x 5.5 x 1.05 mm SOT536-1

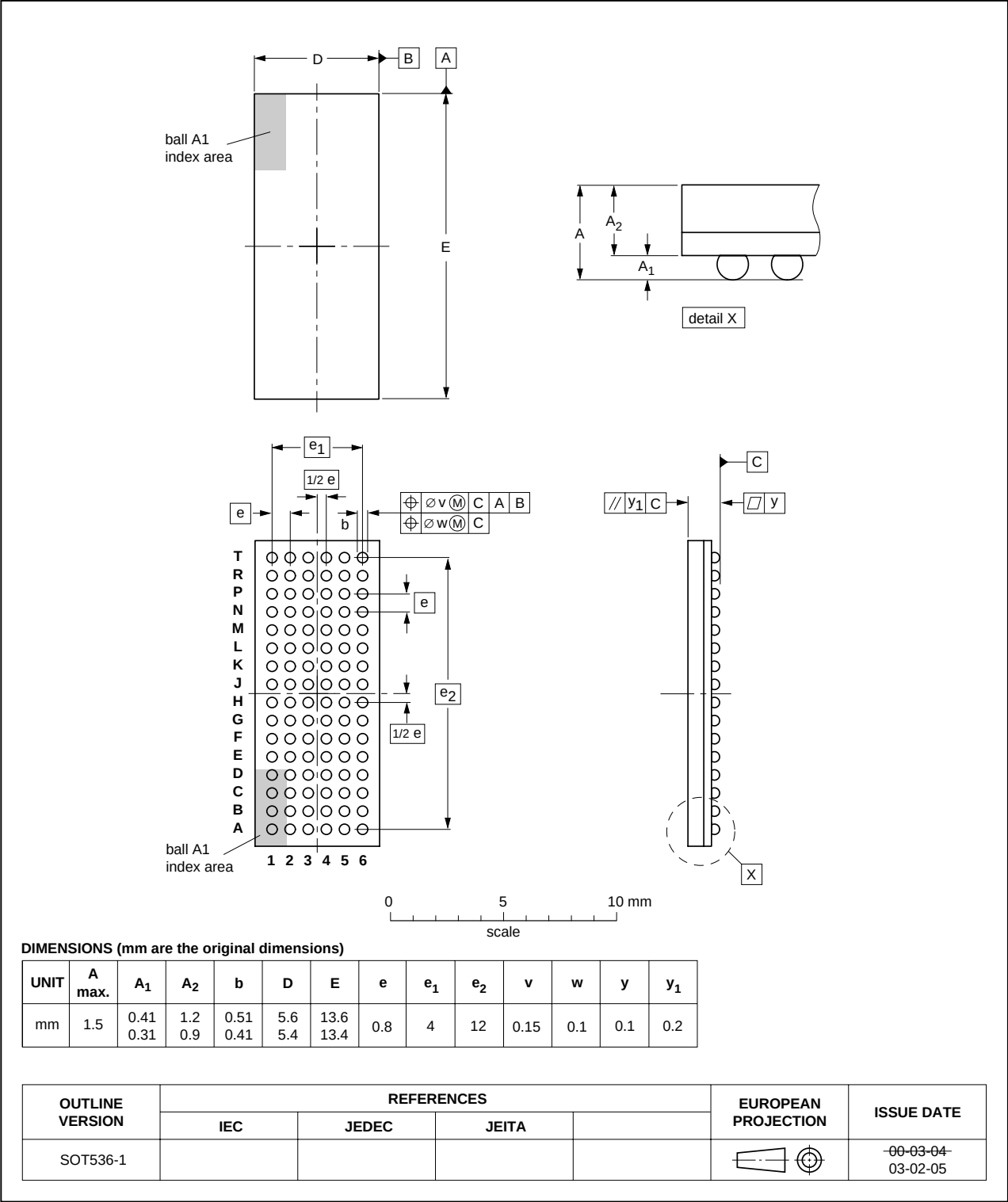


Fig 27. Package outline SOT536-1 (LFBGA96)

## 13. Soldering

### 13.1 Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *Data Handbook IC26; Integrated Circuit Packages* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

### 13.2 Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement. Driven by legislation and environmental forces the worldwide use of lead-free solder pastes is increasing.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 seconds and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 °C to 270 °C depending on solder paste material. The top-surface temperature of the packages should preferably be kept:

- below 225 °C (SnPb process) or below 245 °C (Pb-free process)
  - for all BGA, HTSSON..T and SSOP..T packages
  - for packages with a thickness  $\geq 2.5$  mm
  - for packages with a thickness  $< 2.5$  mm and a volume  $\geq 350$  mm<sup>3</sup> so called thick/large packages.
- below 240 °C (SnPb process) or below 260 °C (Pb-free process) for packages with a thickness  $< 2.5$  mm and a volume  $< 350$  mm<sup>3</sup> so called small/thin packages.

Moisture sensitivity precautions, as indicated on packing, must be respected at all times.

### 13.3 Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;



- smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time of the leads in the wave ranges from 3 seconds to 4 seconds at 250 °C or 265 °C, depending on solder material applied, SnPb or Pb-free respectively.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

### 13.4 Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 seconds to 5 seconds between 270 °C and 320 °C.

### 13.5 Package related soldering information

**Table 11: Suitability of surface mount IC packages for wave and reflow soldering methods**

| Package <sup>[1]</sup>                                                                         | Soldering method                   |                       |
|------------------------------------------------------------------------------------------------|------------------------------------|-----------------------|
|                                                                                                | Wave                               | Reflow <sup>[2]</sup> |
| BGA, HTSSON..T <sup>[3]</sup> , LBGA, LFBGA, SQFP, SSOP..T <sup>[3]</sup> , TFBGA, VFBGA, XSON | not suitable                       | suitable              |
| DHVQFN, HBCC, HBGA, HLQFP, HSO, HSOP, HSQFP, HSSON, HTQFP, HTSSOP, HVQFN, HVSON, SMS           | not suitable <sup>[4]</sup>        | suitable              |
| PLCC <sup>[5]</sup> , SO, SOJ                                                                  | suitable                           | suitable              |
| LQFP, QFP, TQFP                                                                                | not recommended <sup>[5] [6]</sup> | suitable              |
| SSOP, TSSOP, VSO, VSSOP                                                                        | not recommended <sup>[7]</sup>     | suitable              |
| CWQCCN..L <sup>[8]</sup> , PMFP <sup>[9]</sup> , WQCCN..L <sup>[8]</sup>                       | not suitable                       | not suitable          |

[1] For more detailed information on the BGA packages refer to the *(LF)BGA Application Note* (AN01026); order a copy from your Philips Semiconductors sales office.

[2] All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the *Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods*.

[3] These transparent plastic packages are extremely sensitive to reflow soldering conditions and must on no account be processed through more than one soldering cycle or subjected to infrared reflow soldering with peak temperature exceeding 217 °C ± 10 °C measured in the atmosphere of the reflow oven. The package body peak temperature must be kept as low as possible.

- [4] These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.
- [5] If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
- [6] Wave soldering is suitable for LQFP, QFP and TQFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
- [7] Wave soldering is suitable for SSOP, TSSOP, VSO and VSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.
- [8] Image sensor packages in principle should not be soldered. They are mounted in sockets or delivered pre-mounted on flex foil. However, the image sensor package can be mounted by the client on a flex foil by using a hot bar soldering process. The appropriate soldering profile can be provided on request.
- [9] Hot bar soldering or manual soldering is suitable for PMFP packages.

## 14. Abbreviations

**Table 12: Abbreviations**

| Acronym | Description                                   |
|---------|-----------------------------------------------|
| CMOS    | Complementary Metal Oxide Silicon             |
| DDR     | Double Data Rate                              |
| DIMM    | Dual In-line Memory Module                    |
| JEDEC   | Joint Electron Device Engineering Council     |
| LFBGA   | Low profile Fine-pitch Ball Grid Array        |
| LVC MOS | Low Voltage Complementary Metal Oxide Silicon |
| PPO     | Partial Parity Out                            |
| PRR     | Pulse Repetition Rate                         |
| RDIMM   | Registered Dual In-line Memory Module         |
| SSTL    | Stub Series Terminated Logic                  |

## 15. Revision history

**Table 13: Revision history**

| Document ID                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           | Release date | Data sheet status  | Change notice | Doc. number    | Supersedes   |
|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------|--------------------|---------------|----------------|--------------|
| SSTU32866_2                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           | 20041111     | Product data sheet | -             | 9397 750 14181 | SSTU32866-01 |
| Modifications: <ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new presentation and information standard of Philips Semiconductors.</li> <li>Data sheet status upgraded to 'Product data sheet'.</li> <li>(Old) Figure 1 and Figure 2 (logic diagrams) moved to <a href="#">Section 5 "Functional diagram"</a></li> <li><a href="#">Section 6 "Pinning information"</a> <ul style="list-style-type: none"> <li>changed 'NC' to 'n.c.' and 'DNU' to 'd.n.u.'</li> <li>added <a href="#">Figure 3 "Pin configuration for LFBGA96"</a></li> <li>added <a href="#">Figure 4</a>, <a href="#">Figure 5</a>, and <a href="#">Figure 6</a> (replacing old Tables 2, 3 and 4 "Ball mapping")</li> <li><a href="#">Table 2 "Pin description"</a>: added (new) <a href="#">Table note [1]</a> and its references at affected pins.; added pin number column.</li> </ul> </li> <li><a href="#">Table 3 "Function table (each flip-flop)"</a>: added <a href="#">Table note [1]</a> and its reference at 'Outputs'.</li> <li><a href="#">Table 4 "Parity and standby function table"</a>:               <ul style="list-style-type: none"> <li>added (new) <a href="#">Table note [1]</a> and its reference at 'Outputs'.</li> <li><a href="#">Table note [4]</a>: changed 'This transition assumes ...' to 'This condition assumes ...'.</li> </ul> </li> <li><a href="#">Table 5 "Limiting values"</a>:               <ul style="list-style-type: none"> <li>symbol <math>V_i</math> changed to <math>V_I</math>; Symbol <math>V_o</math> changed to <math>V_O</math>.</li> <li>symbols ESD<sub>HBM</sub> and ESD<sub>MM</sub> replaced with <math>V_{esd}</math> (added model types under "Conditions")</li> </ul> </li> <li><a href="#">Table 6 "Recommended operating conditions"</a>:               <ul style="list-style-type: none"> <li>changed column heading from 'Nom' to 'Typ'</li> <li>changed <math>V_{IH}</math> (for Data, <math>\overline{CSR}</math>, and PAR_IN inputs) to <math>V_{IH(AC)}</math> and <math>V_{IH(DC)}</math>; condition changed to 'data inputs (Dn) ...'</li> <li>changed <math>V_{IL}</math> (for Data, <math>\overline{CSR}</math>, and PAR_IN inputs) to <math>V_{IL(AC)}</math> and <math>V_{IL(DC)}</math>; condition changed to 'data inputs (Dn)'</li> <li>table note split into 2 notes; references added.</li> </ul> </li> <li>merged sections "Static characteristics" and "Dynamic characteristics" into <a href="#">Section 10 "Characteristics"</a></li> <li><a href="#">Table 7 "Characteristics"</a>: changed <math>I_{DD}</math> Parameter from "dynamic operating current ..." to "dynamic operating current per MHz ..."; change Unit from "μA/MHz" to "μA".</li> <li><a href="#">Table 8 "Timing requirements"</a>:               <ul style="list-style-type: none"> <li>changed symbol <math>f_{CLOCK}</math> to <math>f_{clock}</math></li> <li>changed symbol <math>t_{SU}</math> to <math>t_{su}</math></li> <li>changed symbol <math>t_H</math> to <math>t_h</math></li> </ul> </li> <li><a href="#">Figure 7</a> modified.</li> <li><a href="#">Section 11.1 "Parameter measurement information for data output load circuit"</a>: titles for <a href="#">Figure 14</a> and <a href="#">Figure 15</a> modified.</li> <li>added <a href="#">Section 14</a>.</li> </ul> |              |                    |               |                |              |
| SSTU32866-01                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                          | 20040709     | Objective data     | -             | 9397 750 12145 | -            |

## 16. Data sheet status

| Level | Data sheet status <sup>[1]</sup> | Product status <sup>[2] [3]</sup> | Definition                                                                                                                                                                                                                                                                                     |
|-------|----------------------------------|-----------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| I     | Objective data                   | Development                       | This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.                                                                                                    |
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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

## 17. Definitions

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## 20. Contents

|           |                                                                              |           |
|-----------|------------------------------------------------------------------------------|-----------|
| <b>1</b>  | <b>General description</b> .....                                             | <b>1</b>  |
| <b>2</b>  | <b>Features</b> .....                                                        | <b>1</b>  |
| <b>3</b>  | <b>Applications</b> .....                                                    | <b>2</b>  |
| <b>4</b>  | <b>Ordering information</b> .....                                            | <b>2</b>  |
| <b>5</b>  | <b>Functional diagram</b> .....                                              | <b>3</b>  |
| <b>6</b>  | <b>Pinning information</b> .....                                             | <b>5</b>  |
| 6.1       | Pinning .....                                                                | 5         |
| 6.2       | Pin description .....                                                        | 7         |
| <b>7</b>  | <b>Functional description</b> .....                                          | <b>8</b>  |
| 7.1       | Function table .....                                                         | 10        |
| <b>8</b>  | <b>Limiting values</b> .....                                                 | <b>11</b> |
| <b>9</b>  | <b>Recommended operating conditions</b> .....                                | <b>11</b> |
| <b>10</b> | <b>Characteristics</b> .....                                                 | <b>12</b> |
| 10.1      | Timing diagrams .....                                                        | 14        |
| <b>11</b> | <b>Test information</b> .....                                                | <b>17</b> |
| 11.1      | Parameter measurement information for<br>data output load circuit .....      | 17        |
| 11.2      | Data output slew rate measurement<br>information .....                       | 19        |
| 11.3      | Error output load circuit and voltage<br>measurement information .....       | 20        |
| 11.4      | Partial Parity Out load circuit and voltage<br>measurement information ..... | 21        |
| <b>12</b> | <b>Package outline</b> .....                                                 | <b>23</b> |
| <b>13</b> | <b>Soldering</b> .....                                                       | <b>24</b> |
| 13.1      | Introduction to soldering surface mount<br>packages .....                    | 24        |
| 13.2      | Reflow soldering .....                                                       | 24        |
| 13.3      | Wave soldering .....                                                         | 24        |
| 13.4      | Manual soldering .....                                                       | 25        |
| 13.5      | Package related soldering information .....                                  | 25        |
| <b>14</b> | <b>Abbreviations</b> .....                                                   | <b>26</b> |
| <b>15</b> | <b>Revision history</b> .....                                                | <b>27</b> |
| <b>16</b> | <b>Data sheet status</b> .....                                               | <b>28</b> |
| <b>17</b> | <b>Definitions</b> .....                                                     | <b>28</b> |
| <b>18</b> | <b>Disclaimers</b> .....                                                     | <b>28</b> |
| <b>19</b> | <b>Contact information</b> .....                                             | <b>28</b> |



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